

MSLIN98-001

In the claims:

Claims ~~31-36~~ are hereby canceled.

Please add the following claim:

37. A wafer scale package, comprising:

a semiconductor wafer, including chip images separated by a kerf area and having a topmost passivating layer through which pass connecting studs;

A | a body of silicone elastomer on said topmost passivating layer, having a plurality of metal posts in contact with, and fixed to, said connecting studs and passing vertically through said body of silicone elastomer from said studs ;

said posts being of a diameter and height and of a material such that they can bend to absorb stress due to thermal mismatch between said semiconductor wafer and said body of silicone elastomer; and

wherein said body of silicon elastomer can also absorb stress due to said thermal mismatch.